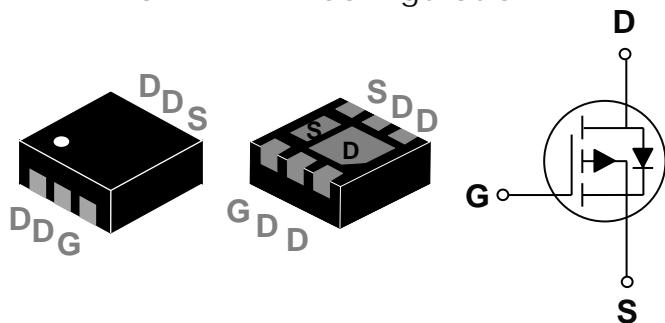


20V P-ChannelMOSFETs**General Description**

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

DFN2x2-6L 2EP Pin Configuration

BVDSS	RDS(ON)	ID
-20V	28mΩ	-8.5A

Features

- -20V,-8.5A, RDS(ON) =28mΩ @VGS = -4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	-8.5	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	-5.4	A
I_{DM}	Drain Current – Pulsed ¹	-34	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	3.3	W
	Power Dissipation – Derate above 25°C	0.026	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	38	°C/W



FTK2309DFN22

20V P-ChannelMOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	---	-0.02	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 10\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-4\text{A}$	---	22	28	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$, $I_{\text{D}}=-3\text{A}$	---	27	37	
		$V_{\text{GS}}=-1.8\text{V}$, $I_{\text{D}}=-2\text{A}$	---	33	45	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-0.3	-0.6	-1	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	2	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_{\text{S}}=-3\text{A}$	---	8.4	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2, 3}	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-4\text{A}$	---	16.1	25	nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	1.8	3	
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	3.8	7	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{2, 3}	$V_{\text{DD}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $R_{\text{G}}=25\Omega$ $I_{\text{D}}=-1\text{A}$	---	8.2	16	nS
T_r	Rise Time ^{2, 3}		---	30	57	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{2, 3}		---	71.1	135	
T_f	Fall Time ^{2, 3}		---	19.8	38	
C_{iss}	Input Capacitance		---	1440	2100	pF
C_{oss}	Output Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	155	230	
C_{rss}	Reverse Transfer Capacitance		---	115	170	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-8.5	A
I_{SM}	Pulsed Source Current		---	---	-17	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

20V P-ChannelMOSFETs

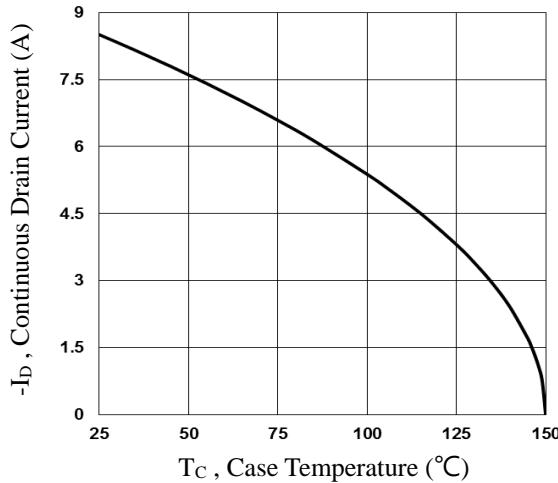


Fig.1 Continuous Drain Current vs. T_c

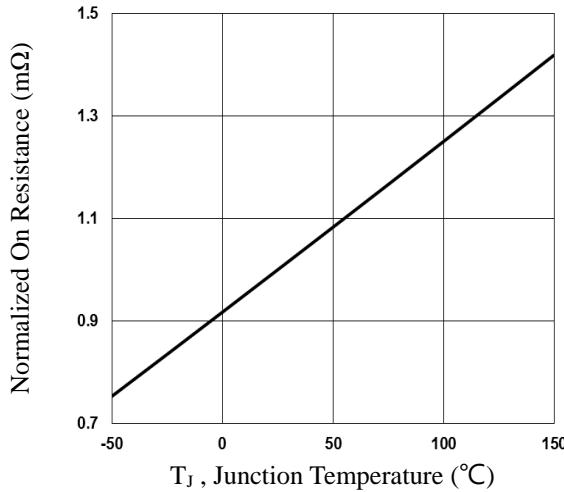


Fig.2 Normalized RDSON vs. T_J

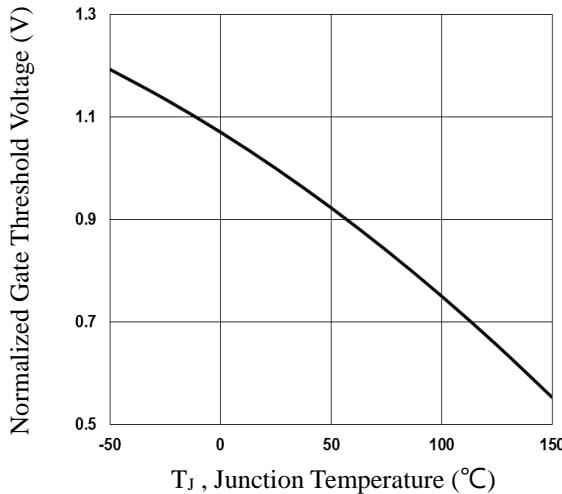


Fig.3 Normalized V_{th} vs. T_J

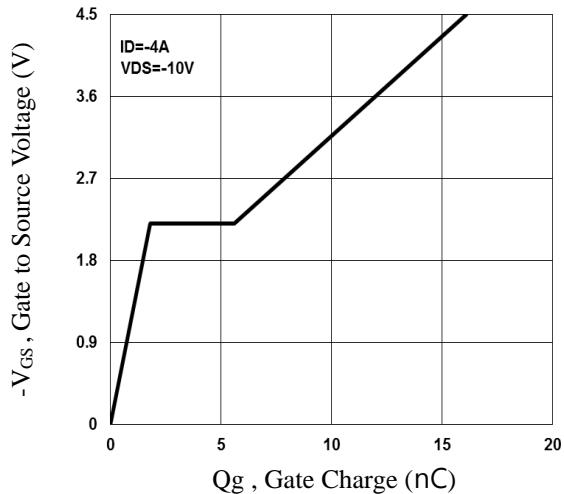


Fig.4 Gate Charge Waveform

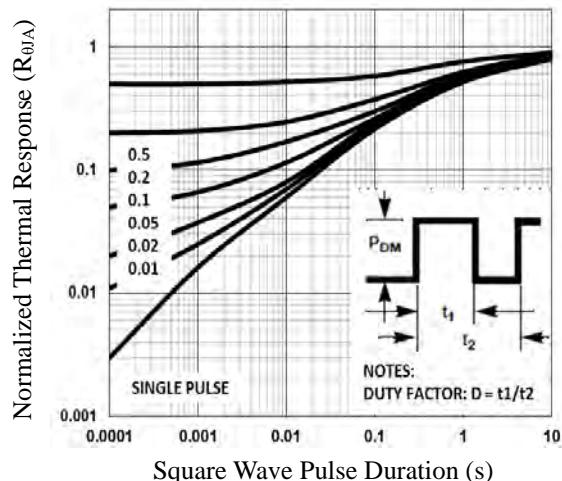


Fig.5 Normalized Transient Impedance

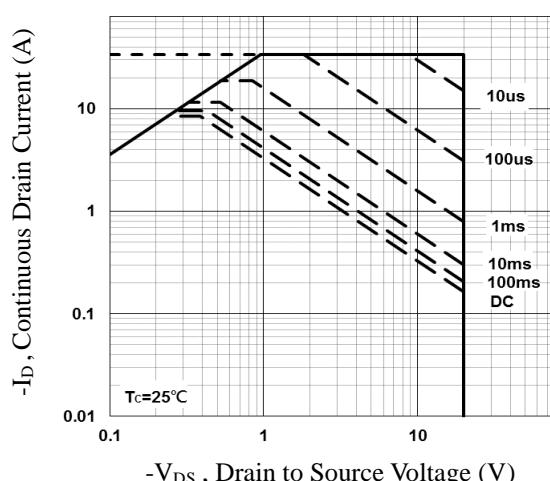


Fig.6 Maximum Safe Operation Area

20V P-Channel MOSFETs

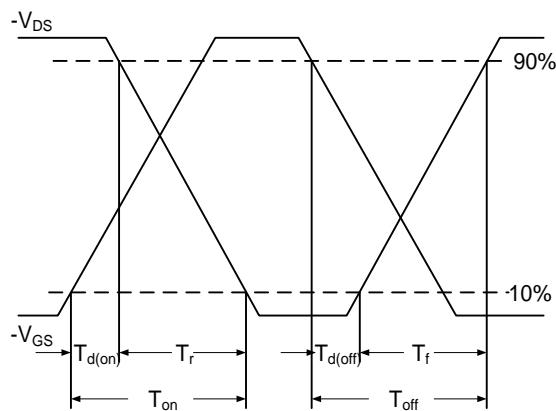


Fig.7 Switching Time Waveform

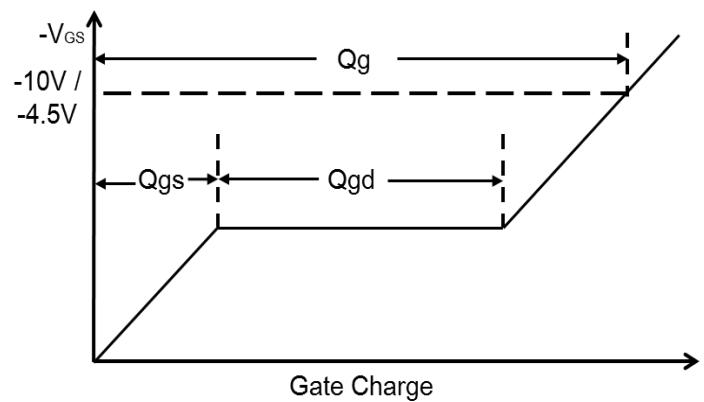
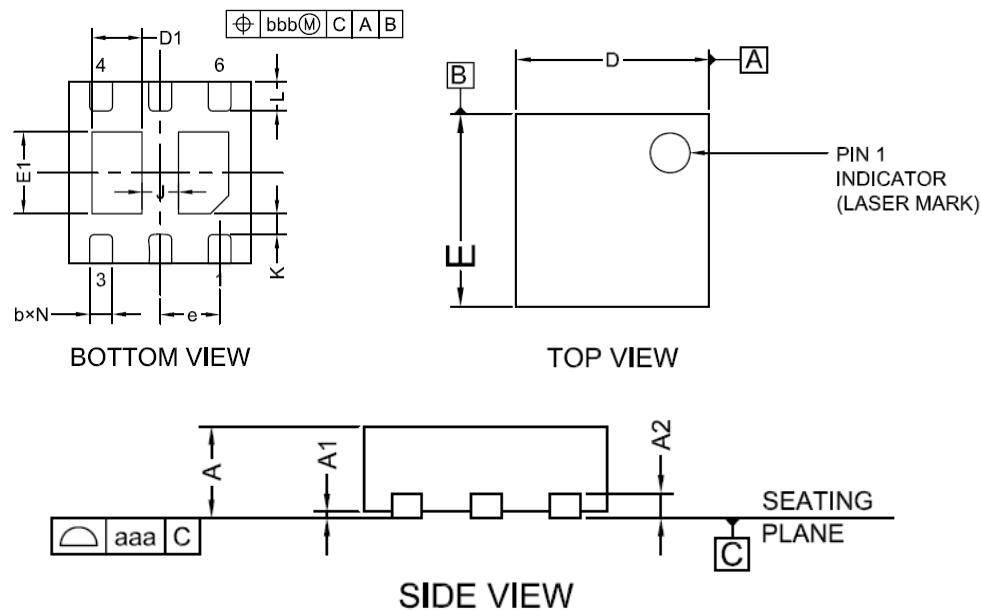


Fig.8 Gate Charge Waveform

20V P-ChannelMOSFETs

DFN2x2-6L 2EP PACKAGE INFORMATION



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2		0.203	
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D1	0.50	0.55	0.60
E	1.95	2.00	2.05
E1	0.85	0.90	0.95
e		0.65BSC	
L	0.27	0.32	0.37
J		0.40BSC	
K		0.20MIN	
N		6	
aaa		0.08	
bbb		0.10	